

Product/Process Change Notice - PCN 17_0215 Rev. -

Analog Devices, Inc. Three Technology Way Norwood, Massachusetts 02062-9106

This notice is to inform you of a change that will be made to certain ADI products (see Appendix A) that you may have purchased in the last 2 years. Any inquiries or requests with this PCN (additional data or samples) must be sent to ADI within 30 days of publication date. ADI contact information is listed below.

PCN Title: Change to Assembly Die Bond Epoxy and Mold Compound Materials for AD5532

CSP BGA Products

Publication Date: 08-Jan-2018

Effectivity Date: 12-Apr-2018 (the earliest date that a customer could expect to receive changed material)
Revision Description:
Initial Release
Description Of Change
Assembly epoxy mold compound and die bond epoxy material changes from HC100XJAA/A2000 to the qualified G7730L/CRM1525 for AD5532 CSP_BGA products.
Reason For Change
Epoxy Manufacturer has notified ADI of the discontinuation of epoxy mold compound series (Hitachi HC100XJAA). Due to this change; the epoxy die bond material along with the epoxy mold compound will be changed to already qualified materials currently in use for generic part AD5532.
Impact of the change (positive or negative) on fit, form, function & reliability
There will be no impact on the form, fit, function or reliability of the devices.
Product Identification (this section will describe how to identify the changed material)
The parts will be identified by assembly lot and the country of origin.
Summary of Supporting Information
Qualification will be performed per Industry Standard Test Methods. See attached Qualification Plan.

Supporting Documents

Attachment 1: Type: Qualification Results Summary

ADI_PCN_17_0215_Rev_- Qualification Result Summary for AD5532 CSP_BGA with G7730L CRM1525.pdf

For questions on this PCN, please send an email to the regional contacts below or contact your local ADI sales representatives.

Americas: PCN_Americas@analog.com Europe: PCN_Europe@analog.com Japan: PCN_Japan@analog.com

PCN_ROA@analog.com Rest of Asia:

Appendix A - Affected ADI Models					
Added Parts On This Revision - Product Family / Model Number (2)					
AD5532 / AD11/2031-0	AD5532HS / AD5532HSABCZ				

Appendix B - Revision History					
Rev	Publish Date	Effectivity Date	Rev Description		
Rev	08-Jan-2018	12-Apr-2018	Initial Release		

Analog Devices, Inc.

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